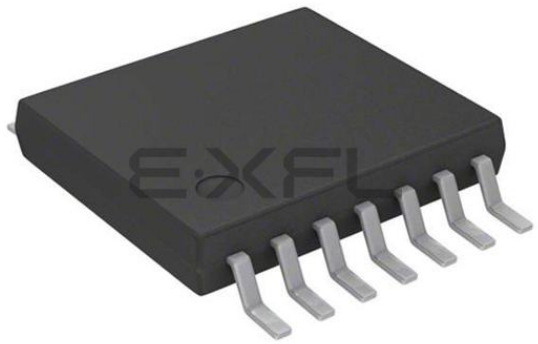

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	11
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	14-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	14-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1503-e-st

3.0 MEMORY ORGANIZATION

These devices contain the following types of memory:

- Program Memory
  - Configuration Words
  - Device ID
  - User ID
  - Flash Program Memory
- Data Memory
  - Core Registers
  - Special Function Registers
  - General Purpose RAM
  - Common RAM

The following features are associated with access and control of program memory and data memory:

- PCL and PCLATH
- Stack
- Indirect Addressing

3.1 Program Memory Organization

The enhanced mid-range core has a 15-bit program counter capable of addressing a 32K x 14 program memory space. Table 3-1 shows the memory sizes implemented. Accessing a location above these boundaries will cause a wrap-around within the implemented memory space. The Reset vector is at 0000h and the interrupt vector is at 0004h (See Figure 3-1).

3.2 High-Endurance Flash

This device has a 128 byte section of high-endurance program Flash memory (PFM) in lieu of data EEPROM. This area is especially well suited for nonvolatile data storage that is expected to be updated frequently over the life of the end product. See **Section 10.2 "Flash Program Memory Overview"** for more information on writing data to PFM. See **Section 3.2.1.2 "Indirect Read with FSR"** for more information about using the FSR registers to read byte data stored in PFM.

TABLE 3-1: DEVICE SIZES AND ADDRESSES

Device	Program Memory Space (Words)	Last Program Memory Address	High-Endurance Flash Memory Address Range (1)
PIC16LF1503 PIC16F1503	2,048	07FFh	0780h-07FFh

Note 1: High-endurance Flash applies to low byte of each address in the range.

REGISTER 7-2: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1

R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	U-0	R/W-0/0	R/W-0/0
TMR1GIE	ADIE	—	—	SSP1IE	—	TMR2IE	TMR1IE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **TMR1GIE:** Timer1 Gate Interrupt Enable bit
1 = Enables the Timer1 gate acquisition interrupt
0 = Disables the Timer1 gate acquisition interrupt

bit 6 **ADIE:** Analog-to-Digital Converter (ADC) Interrupt Enable bit
1 = Enables the ADC interrupt
0 = Disables the ADC interrupt

bit 5-4 **Unimplemented:** Read as '0'

bit 3 **SSP1IE:** Synchronous Serial Port (MSSP) Interrupt Enable bit
1 = Enables the MSSP interrupt
0 = Disables the MSSP interrupt

bit 2 **Unimplemented:** Read as '0'

bit 1 **TMR2IE:** TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the Timer2 to PR2 match interrupt
0 = Disables the Timer2 to PR2 match interrupt

bit 0 **TMR1IE:** Timer1 Overflow Interrupt Enable bit
1 = Enables the Timer1 overflow interrupt
0 = Disables the Timer1 overflow interrupt

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

REGISTER 7-4: PIE3: PERIPHERAL INTERRUPT ENABLE REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	—	—	—	—	CLC2IE	CLC1IE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Unimplemented:** Read as ‘0’

bit 1 **CLC2IE:** Configurable Logic Block 2 Interrupt Enable bit
- 1 = Enables the CLC 2 interrupt
- 0 = Disables the CLC 2 interrupt

bit 0 **CLC1IE:** Configurable Logic Block 1 Interrupt Enable bit
- 1 = Enables the CLC 1 interrupt
- 0 = Disables the CLC 1 interrupt

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

TABLE 7-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	64
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			139
PIE1	TMR1GIE	ADIE	—	—	SSP1IE	—	TMR2IE	TMR1IE	65
PIE2	—	C2IE	C1IE	—	BCL1IE	NCO1IE	—	—	66
PIE3	—	—	—	—	—	—	CLC2IE	CLC1IE	67
PIR1	TMR1GIF	ADIF	—	—	SSP1IF	—	TMR2IF	TMR1IF	68
PIR2	—	C2IF	C1IF	—	BCL1IF	NCO1IF	—	—	69
PIR3	—	—	—	—	—	—	CLC2IF	CLC1IF	70

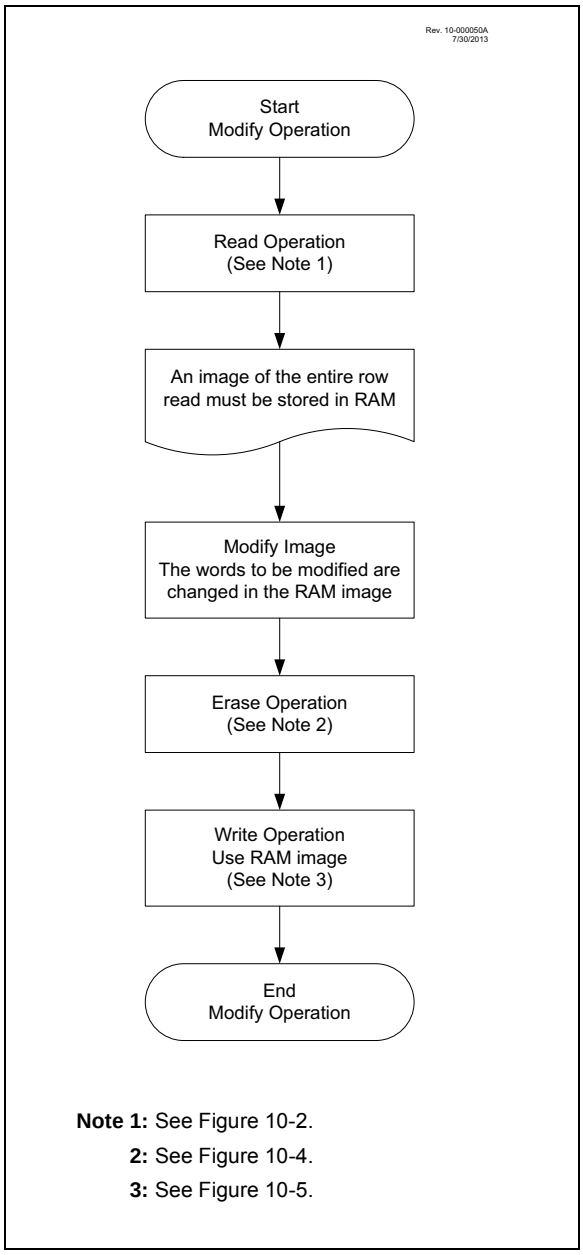
Legend: — = unimplemented location, read as '0'. Shaded cells are not used by interrupts.

10.3 Modifying Flash Program Memory

When modifying existing data in a program memory row, and data within that row must be preserved, it must first be read and saved in a RAM image. Program memory is modified using the following steps:

1. Load the starting address of the row to be modified.
2. Read the existing data from the row into a RAM image.
3. Modify the RAM image to contain the new data to be written into program memory.
4. Load the starting address of the row to be rewritten.
5. Erase the program memory row.
6. Load the write latches with data from the RAM image.
7. Initiate a programming operation.

FIGURE 10-7: FLASH PROGRAM MEMORY MODIFY FLOWCHART



Note 1: See Figure 10-2.
2: See Figure 10-4.
3: See Figure 10-5.

10.6 Register Definitions: Flash Program Memory Control

REGISTER 10-1: PMDATL: PROGRAM MEMORY DATA LOW BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PMDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PMDAT<7:0>**: Read/write value for Least Significant bits of program memory

REGISTER 10-2: PMDATH: PROGRAM MEMORY DATA HIGH BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	PMDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **PMDAT<13:8>**: Read/write value for Most Significant bits of program memory

REGISTER 10-3: PMADRL: PROGRAM MEMORY ADDRESS LOW BYTE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PMADR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PMADR<7:0>**: Specifies the Least Significant bits for program memory address

REGISTER 10-4: PMADRH: PROGRAM MEMORY ADDRESS HIGH BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—(1)	PMADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘1’

bit 6-0 **PMADR<14:8>**: Specifies the Most Significant bits for program memory address

Note 1: Unimplemented, read as ‘1’.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are 11 channel selections available:

- AN<7:0> pins
- Temperature Indicator
- FVR_buffer1

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay (T_{ACQ}) is required before starting the next conversion. Refer to **Section 15.2.6 "ADC Conversion Procedure"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADC module uses a positive and a negative voltage reference. The positive reference is labeled ref+ and the negative reference is labeled ref-.

The positive voltage reference (ref+) is selected by the ADPREF bits in the ADCON1 register. The positive voltage reference source can be:

- V_{REF}+ pin
- V_{DD}

The negative voltage reference (ref-) source is:

- V_{SS}

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- F_{OSC}/2
- F_{OSC}/4
- F_{OSC}/8
- F_{OSC}/16
- F_{OSC}/32
- F_{OSC}/64
- FRC (internal RC oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 10-bit conversion requires 11.5 T_{AD} periods as shown in Figure 15-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the ADC conversion requirements in **Section 28.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

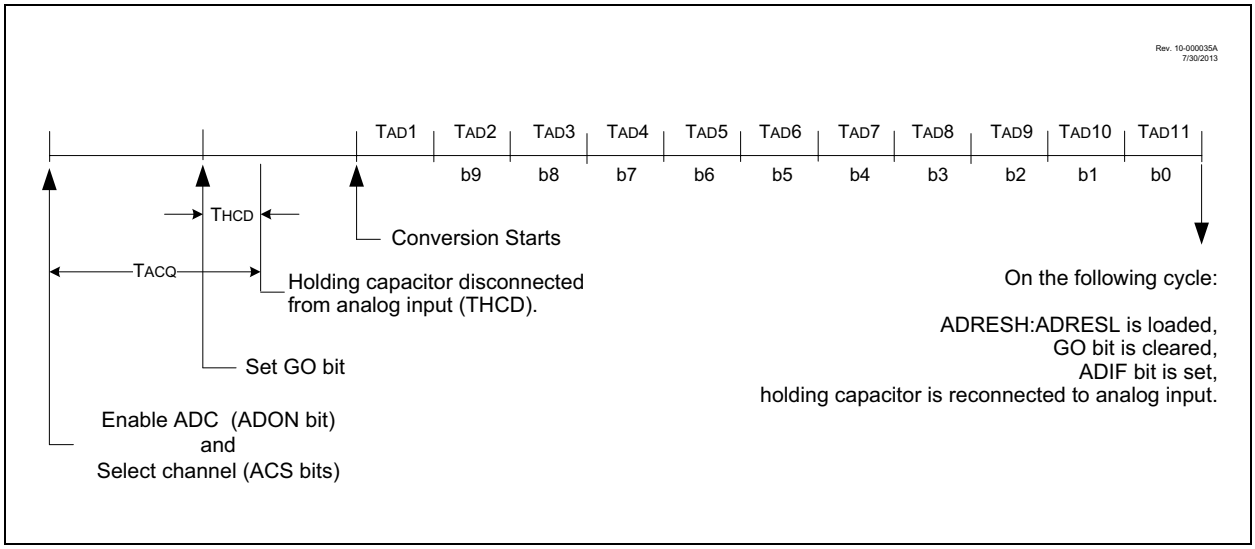
TABLE 15-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})				
ADC Clock Source	ADCS<2:0>	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz
Fosc/2	000	100 ns	125 ns	250 ns	500 ns	2.0 μs
Fosc/4	100	200 ns	250 ns	500 ns	1.0 μs	4.0 μs
Fosc/8	001	400 ns	500 ns	1.0 μs	2.0 μs	8.0 μs
Fosc/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs
Fosc/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs	32.0 μs
Fosc/64	110	3.2 μs	4.0 μs	8.0 μs	16.0 μs	64.0 μs
FRC	x11	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs	1.0-6.0 μs

Legend: Shaded cells are outside of recommended range.

Note: The T_{AD} period when using the FRC clock source can fall within a specified range, (see T_{AD} parameter). The T_{AD} period when using the F_{OSC}-based clock source can be configured for a more precise T_{AD} period. However, the FRC clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 15-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



15.4 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (C_{HOLD}) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 15-4. The source impedance (R_S) and the internal sampling switch (R_{SS}) impedance directly affect the time required to charge the capacitor C_{HOLD}. The sampling switch (R_{SS}) impedance varies over the device voltage (V_{DD}), refer to Figure 15-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 15-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 15-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -12.5pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.72\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 1.72\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.97\mu s$$

Note 1: The reference voltage (V_{RPOS}) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (C_{HOLD}) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

21.2 SPI Mode Overview

The Serial Peripheral Interface (SPI) bus is a synchronous serial data communication bus that operates in Full-Duplex mode. Devices communicate in a master/slave environment where the master device initiates the communication. A slave device is controlled through a Chip Select known as Slave Select.

The SPI bus specifies four signal connections:

- Serial Clock (SCKx)
- Serial Data Out (SDOx)
- Serial Data In (SDIx)
- Slave Select ($\overline{SSx}$)

Figure 21-1 shows the block diagram of the MSSP module when operating in SPI mode.

The SPI bus operates with a single master device and one or more slave devices. When multiple slave devices are used, an independent Slave Select connection is required from the master device to each slave device.

Figure 21-4 shows a typical connection between a master device and multiple slave devices.

The master selects only one slave at a time. Most slave devices have tri-state outputs so their output signal appears disconnected from the bus when they are not selected.

Transmissions involve two shift registers, eight bits in size, one in the master and one in the slave. With either the master or the slave device, data is always shifted out one bit at a time, with the Most Significant bit (MSb) shifted out first. At the same time, a new Least Significant bit (LSb) is shifted into the same register.

Figure 21-5 shows a typical connection between two processors configured as master and slave devices.

Data is shifted out of both shift registers on the programmed clock edge and latched on the opposite edge of the clock.

The master device transmits information out on its SDOx output pin which is connected to, and received by, the slave's SDIx input pin. The slave device transmits information out on its SDOx output pin, which is connected to, and received by, the master's SDIx input pin.

To begin communication, the master device first sends out the clock signal. Both the master and the slave devices should be configured for the same clock polarity.

The master device starts a transmission by sending out the MSb from its shift register. The slave device reads this bit from that same line and saves it into the LSb position of its shift register.

During each SPI clock cycle, a full-duplex data transmission occurs. This means that while the master device is sending out the MSb from its shift register (on its SDOx pin) and the slave device is reading this bit and saving it as the LSb of its shift register, that the slave device is also sending out the MSb from its shift register (on its SDOx pin) and the master device is reading this bit and saving it as the LSb of its shift register.

After eight bits have been shifted out, the master and slave have exchanged register values.

If there is more data to exchange, the shift registers are loaded with new data and the process repeats itself.

Whether the data is meaningful or not (dummy data), depends on the application software. This leads to three scenarios for data transmission:

- Master sends useful data and slave sends dummy data.
- Master sends useful data and slave sends useful data.
- Master sends dummy data and slave sends useful data.

Transmissions may involve any number of clock cycles. When there is no more data to be transmitted, the master stops sending the clock signal and it deselects the slave.

Every slave device connected to the bus that has not been selected through its slave select line must disregard the clock and transmission signals and must not transmit out any data of its own.

TABLE 21-3: SUMMARY OF REGISTERS ASSOCIATED WITH I²C™ OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	64
PIE1	TMR1GIE	ADIE	—	—	SSP1IE	—	TMR2IE	TMR1IE	65
PIE2	—	C2IE	C1IE	—	BCL1IE	NCO1IE	—	—	66
PIR1	TMR1GIF	ADIF	—	—	SSP1IF	—	TMR2IF	TMR1IF	68
PIR2	—	C2IF	C1IF	—	BCL1IF	NCO1IF	—	—	69
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	98
SSP1ADD	ADD<7:0>								207
SSP1BUF	MSSP Receive Buffer/Transmit Register								158*
SSP1CON1	WCOL	SSPOV	SSPEN	CKP	SSPM<3:0>				204
SSP1CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	205
SSP1CON3	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	206
SSP1MSK	MSK<7:0>								207
SSP1STAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	203

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the MSSP module in I²C™ mode.

* Page provides register information.

Note 1: Unimplemented, read as '1'.

REGISTER 21-2: SSPxCON1: SSP CONTROL REGISTER 1

R/C/HS-0/0	R/C/HS-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
WCOL	SSPOV(1)	SSPEN	CKP	SSPM<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets	
'1' = Bit is set	'0' = Bit is cleared	HS = Bit is set by hardware	C = User cleared

bit 7 **WCOL:** Write Collision Detect bit
Master mode:
1 = A write to the SSPxBUF register was attempted while the I^2C conditions were not valid for a transmission to be started
0 = No collision
Slave mode:
1 = The SSPxBUF register is written while it is still transmitting the previous word (must be cleared in software)
0 = No collision

bit 6 **SSPOV:** Receive Overflow Indicator bit(1)
In SPI mode:
1 = A new byte is received while the SSPxBUF register is still holding the previous data. In case of overflow, the data in SSPxSR is lost. Overflow can only occur in Slave mode. In Slave mode, the user must read the SSPxBUF, even if only transmitting data, to avoid setting overflow. In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPxBUF register (must be cleared in software).
0 = No overflow
In I^2C mode:
1 = A byte is received while the SSPxBUF register is still holding the previous byte. SSPOV is a "don't care" in Transmit mode (must be cleared in software).
0 = No overflow

bit 5 **SSPEN:** Synchronous Serial Port Enable bit
In both modes, when enabled, these pins must be properly configured as input or output
In SPI mode:
1 = Enables serial port and configures SCKx, SDOx, SDIx and $\overline{SSx}$ as the source of the serial port pins(2)
0 = Disables serial port and configures these pins as I/O port pins
In I^2C mode:
1 = Enables the serial port and configures the SDAx and SCLx pins as the source of the serial port pins(3)
0 = Disables serial port and configures these pins as I/O port pins

bit 4 **CKP:** Clock Polarity Select bit
In SPI mode:
1 = Idle state for clock is a high level
0 = Idle state for clock is a low level
In I^2C Slave mode:
SCLx release control
1 = Enable clock
0 = Holds clock low (clock stretch). (Used to ensure data setup time.)
In I^2C Master mode:
Unused in this mode

bit 3-0 **SSPM<3:0>:** Synchronous Serial Port Mode Select bits
0000 = SPI Master mode, clock = FOSC/4
0001 = SPI Master mode, clock = FOSC/16
0010 = SPI Master mode, clock = FOSC/64
0011 = SPI Master mode, clock = T2_match/2
0100 = SPI Slave mode, clock = SCKx pin, $\overline{SS}$ pin control enabled
0101 = SPI Slave mode, clock = SCKx pin, $\overline{SS}$ pin control disabled, $\overline{SSx}$ can be used as I/O pin
0110 = I^2C Slave mode, 7-bit address
0111 = I^2C Slave mode, 10-bit address
1000 = I^2C Master mode, clock = FOSC/(4 * (SSPxADD+1))(4)
1001 = Reserved
1010 = SPI Master mode, clock = FOSC/(4 * (SSPxADD+1))(5)
1011 = I^2C firmware controlled Master mode (Slave idle)
1100 = Reserved
1101 = Reserved
1110 = I^2C Slave mode, 7-bit address with Start and Stop bit interrupts enabled
1111 = I^2C Slave mode, 10-bit address with Start and Stop bit interrupts enabled

Note 1: In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPxBUF register.
2: When enabled, these pins must be properly configured as input or output.
3: When enabled, the SDAx and SCLx pins must be configured as inputs.
4: SSPxADD values of 0, 1 or 2 are not supported for I^2C mode.
5: SSPxADD value of '0' is not supported. Use SSPM = 0000 instead.

22.1.5 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is ten bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 22-4.

EQUATION 22-4: PWM RESOLUTION

$$Resolution = \frac{log[4(PR2 + 1)]}{log(2)} \ bits$$

Note: If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

TABLE 22-1: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 20 MHz)

PWM Frequency	0.31 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale	64	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 22-2: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (FOSC = 8 MHz)

PWM Frequency	0.31 kHz	4.90 kHz	19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale	64	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

22.1.6 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the PWMx pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

22.1.7 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency (FOSC). Any changes in the system clock frequency will result in changes to the PWM frequency. Refer to **Section 5.0 "Oscillator Module"** for additional details.

22.1.8 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the PWM registers to their Reset states.

23.1 CLCx Setup

Programming the CLCx module is performed by configuring the four stages in the logic signal flow. The four stages are:

- Data selection
- Data gating
- Logic function selection
- Output polarity

Each stage is setup at run time by writing to the corresponding CLCx Special Function Registers. This has the added advantage of permitting logic reconfiguration on-the-fly during program execution.

23.1.1 DATA SELECTION

There are 16 signals available as inputs to the configurable logic. Four 8-input multiplexers are used to select the inputs to pass on to the next stage. The 16 inputs to the multiplexers are arranged in groups of four. Each group is available to two of the four multiplexers, in each case, paired with a different group. This arrangement makes possible selection of up to two from a group without precluding a selection from another group.

Data selection is through four multiplexers as indicated on the left side of Figure 23-2. Data inputs in the figure are identified by a generic numbered input name.

Table 23-1 correlates the generic input name to the actual signal for each CLC module. The columns labeled lcxd1 through lcxd4 indicate the MUX output for the selected data input. D1S through D4S are abbreviations for the MUX select input codes: LCxD1S<2:0> through LCxD4S<2:0>, respectively. Selecting a data input in a column excludes all other inputs in that column.

Data inputs are selected with CLCxSEL0 and CLCxSEL1 registers (Register 23-3 and Register 23-5, respectively).

Note: Data selections are undefined at power-up.

TABLE 23-1: CLCx DATA INPUT SELECTION

Data Input	lcxd1 D1S	lcxd2 D2S	lcxd3 D3S	lcxd4 D4S	CLC 1	CLC 2
LCx_in[0]	000	—	—	100	CLC1IN0	CLC2IN0
LCx_in[1]	001	—	—	101	CLC1IN1	CLC2IN1
LCx_in[2]	010	—	—	110	C1OUT_sync	C1OUT_sync
LCx_in[3]	011	—	—	111	C2OUT_sync	C2OUT_sync
LCx_in[4]	100	000	—	—	FOSC	FOSC
LCx_in[5]	101	001	—	—	T0_overflow	T0_overflow
LCx_in[6]	110	010	—	—	T1_overflow	T1_overflow
LCx_in[7]	111	011	—	—	T2_match	T2_match
LCx_in[8]	—	100	000	—	LC1_out	LC1_out
LCx_in[9]	—	101	001	—	LC2_out	LC2_out
LCx_in[10]	—	110	010	—	Reserved	Reserved
LCx_in[11]	—	111	011	—	Reserved	Reserved
LCx_in[12]	—	—	100	000	NCO1_out	LFINTOSC
LCx_in[13]	—	—	101	001	HFINTOSC	FRC
LCx_in[14]	—	—	110	010	PWM3_out	PWM1_out
LCx_in[15]	—	—	111	011	PWM4_out	PWM2_out

FIGURE 25-5: SHUTDOWN FUNCTIONALITY, AUTO-RESTART DISABLED (GxARSEN = 0, GxASDLA = 01, GxASDLB = 01)

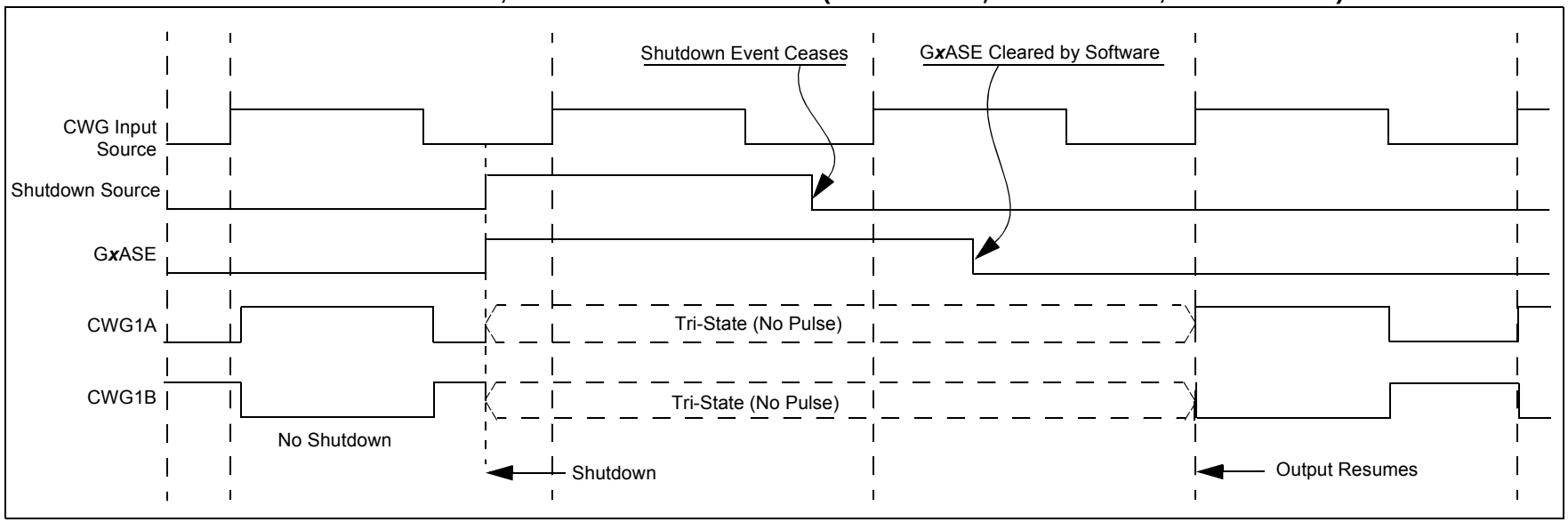


FIGURE 25-6: SHUTDOWN FUNCTIONALITY, AUTO-RESTART ENABLED (GxARSEN = 1, GxASDLA = 01, GxASDLB = 01)

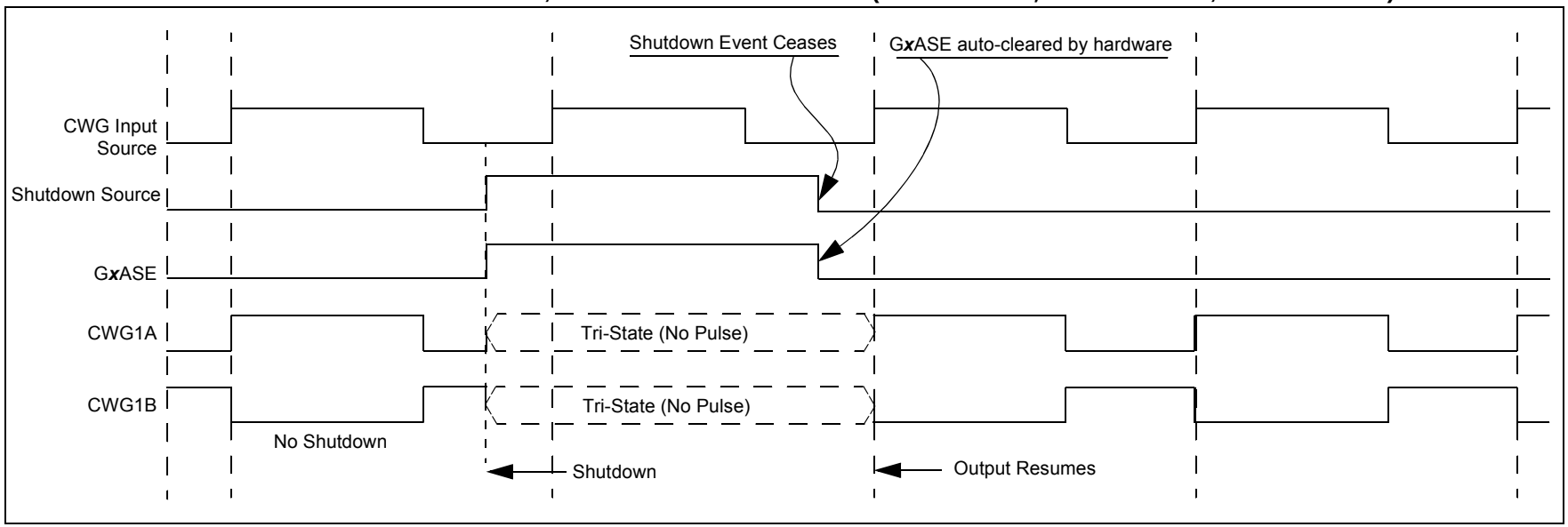


TABLE 28-10: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

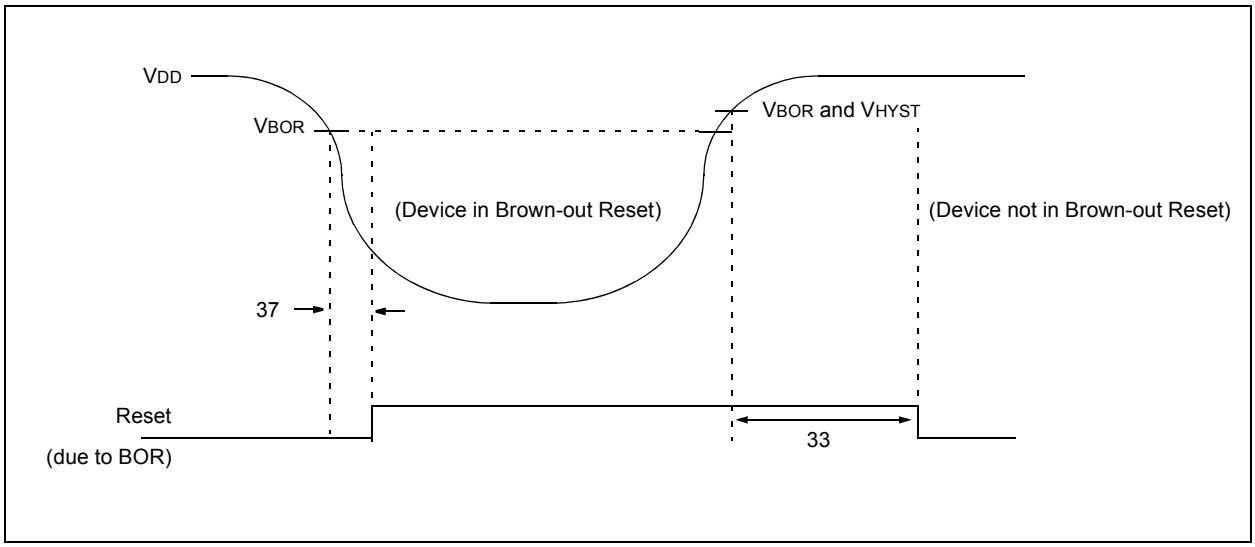
Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{MCLR}$ Pulse Width (low)	2	—	—	μs	
31	TWDTLP	Low-Power Watchdog Timer Time-out Period	10	16	27	ms	VDD = 3.3V-5V, 1:512 Prescaler used
33*	TPWRT	Power-up Timer Period	40	65	140	ms	$\overline{PWRTE}$ = 0
34*	TIOZ	I/O high-impedance from $\overline{MCLR}$ Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage(1)	2.55	2.70	2.85	V	BORV = 0
			2.35	2.45	2.58	V	BORV = 1 (PIC16F1503)
			1.80	1.90	2.05	V	BORV = 1 (PIC16LF1503)
36*	VHYST	Brown-out Reset Hysteresis	0	25	75	mV	-40°C ≤ TA ≤ +85°C
37*	TBORDC	Brown-out Reset DC Response Time	1	16	35	μs	VDD ≤ VBOR
38	VLPBOR	Low-Power Brown-Out Reset Voltage	1.8	2.1	2.5	V	LPBOR = 1

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

FIGURE 28-9: BROWN-OUT RESET TIMING AND CHARACTERISTICS



29.0 DC AND AC CHARACTERISTICS GRAPHS AND CHARTS

The graphs and tables provided in this section are for **design guidance** and are **not tested**.

In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified V_{DD} range). This is for **information only** and devices are ensured to operate properly only within the specified range.

Note:	The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "MAXIMUM", "Max.", "MINIMUM" or "Min." represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over each temperature range.

FIGURE 29-3: IDD, EXTERNAL CLOCK (ECL), LOW-POWER MODE, FOSC = 500 kHz, PIC16LF1503 ONLY

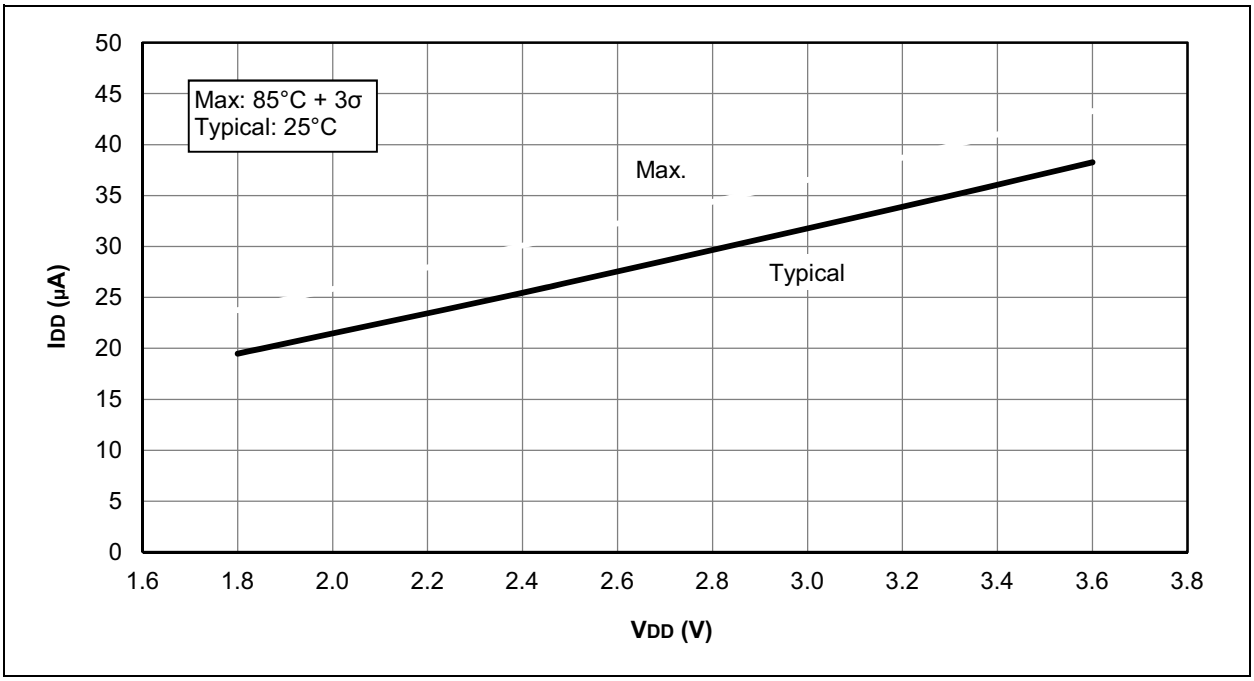


FIGURE 29-4: IDD, EXTERNAL CLOCK (ECL), LOW-POWER MODE, FOSC = 500 kHz, PIC16F1503 ONLY

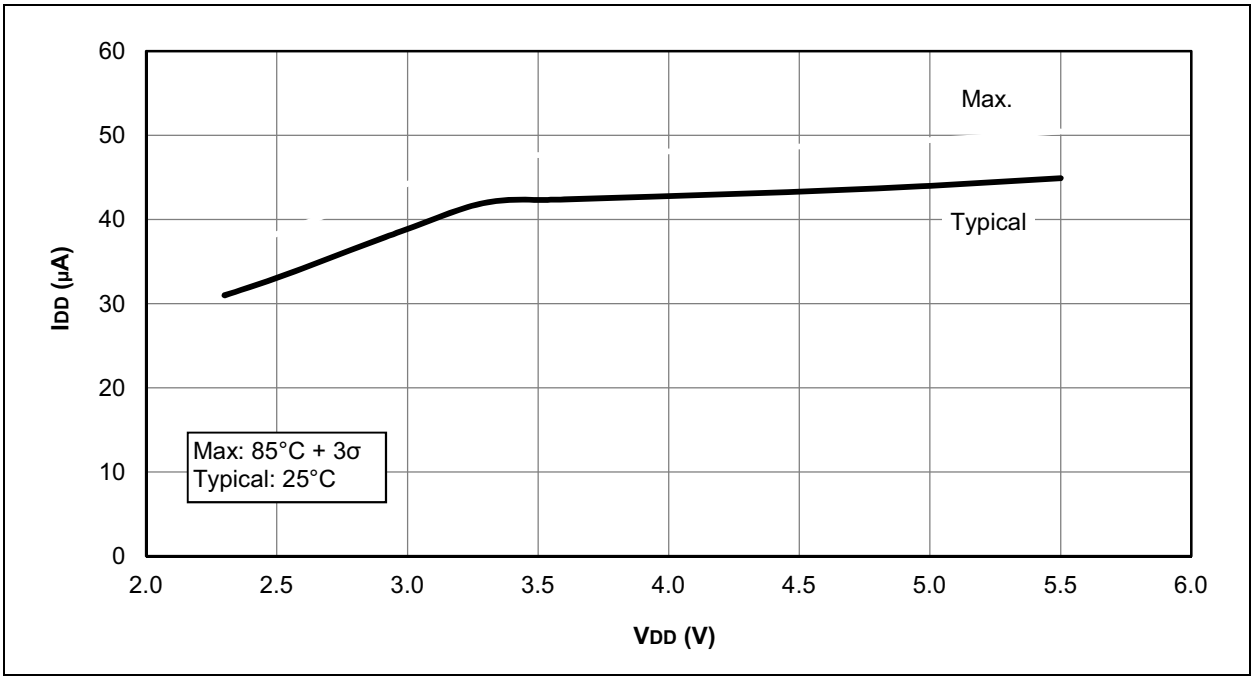


FIGURE 29-19: IDD TYPICAL, HFINTOSC, PIC16F1503 ONLY

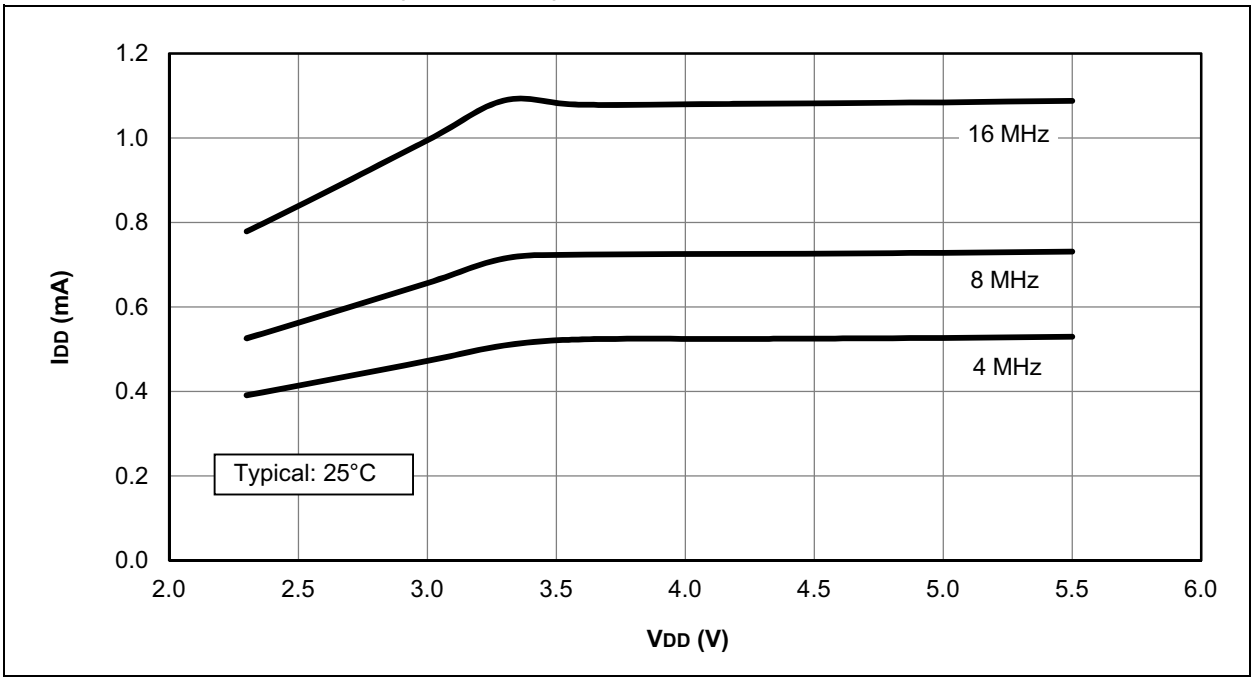


FIGURE 29-20: IDD MAXIMUM, HFINTOSC, PIC16F1503 ONLY

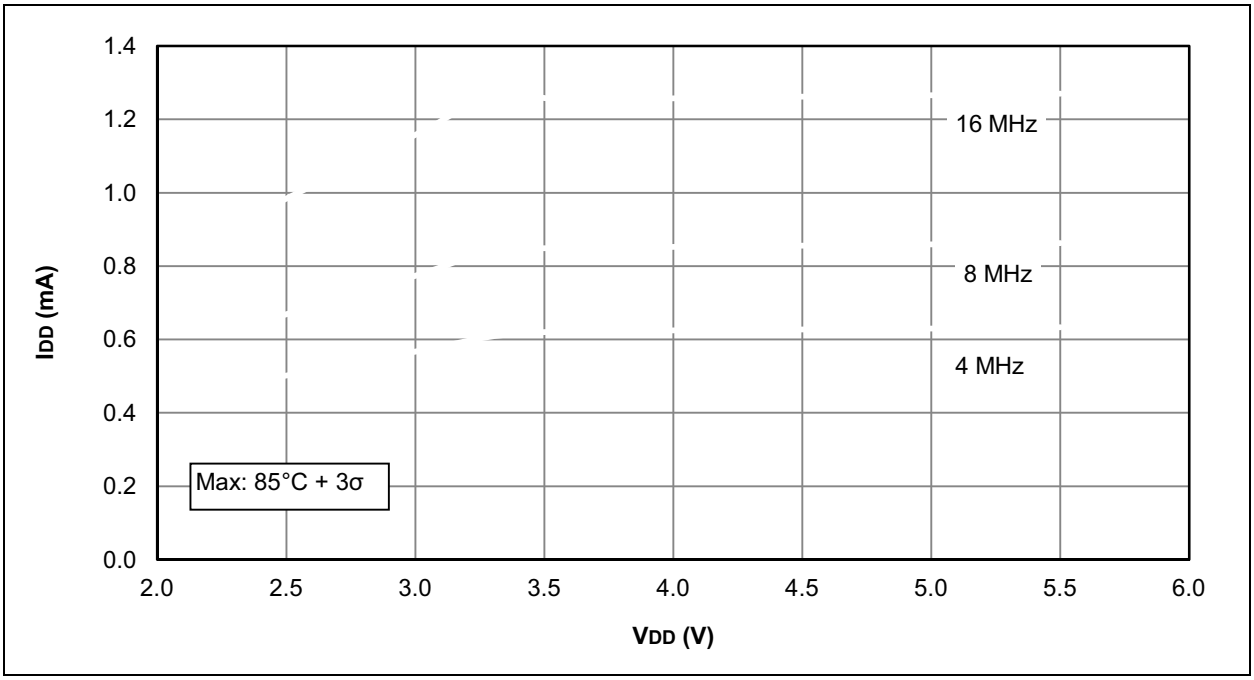


FIGURE 29-55: COMPARATOR RESPONSE TIME, NORMAL POWER MODE (CxSP = 1)

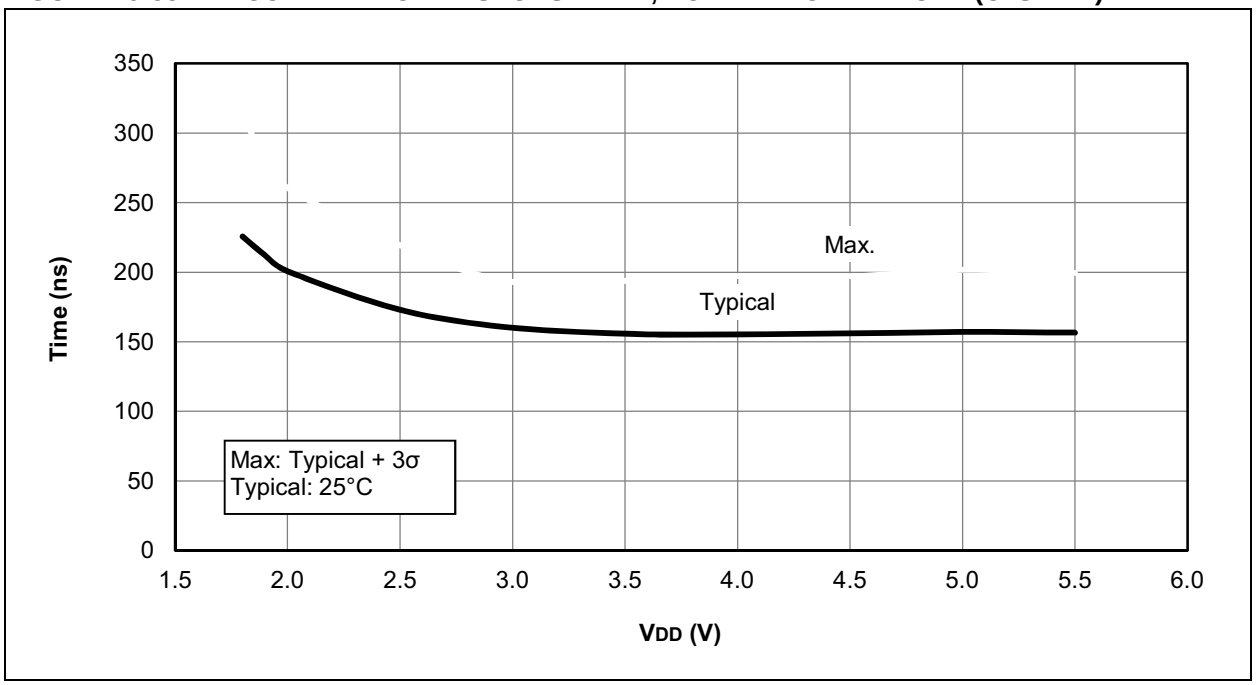


FIGURE 29-56: COMPARATOR RESPONSE TIME OVER TEMPERATURE, NORMAL POWER MODE (CxSP = 1)